or receive a polished workpiece, or supply a workpiece to be polished to the processing section and receive a polished workpiece.

Please replace the paragraph beginning at page 4, line 12, with the following rewritten paragraph:

To achieve the second object described above, according to a second aspect of the present invention, there is provided a polishing apparatus for polishing a semiconductor wafer, comprising: a processing section for polishing a semiconductor wafer; a receiving section for supplying a semiconductor wafer to be polished to the processing section and receiving a polished semiconductor wafer; and a positioning mechanism disposed between the processing section and the receiving section, for aligning a reference position of the semiconductor wafer with a predetermined direction while the semiconductor wafer is transported between the processing section and the receiving section.

Please replace the paragraph beginning at page 8, line 3, with the following rewritten paragraph:

The cleaning section 10 has a discharge device E for forcibly discharging contaminated air in the cleaning section 10 out of the polishing apparatus.

Please replace the paragraph beginning at page 8, line 6, with the following rewritten paragraph:

In FIG. 5, those parts which correspond to those shown in FIG. 6 are denoted by the same references characters as those in FIG. 6 with "1" added thereto. The filter unit 80 is of the same structure as the filter unit 70. The load and unload section 30 has a floor with an air suction port defined therein and communicating with the filter unit 80 in the same manner as described above. The load and unload section 30 also has a discharge device E1 for forcibly discharging contaminated air out of the polishing apparatus in the same manner as described above.

Please replace the paragraph beginning at page 8, line 16, with the following rewritten paragraph:

Since the cleaning section 10, and the clean chamber 20 and the load and unload section 30 are separated from each other by the partition 102, it is sufficient to keep the load and unload section 30 clean for the purpose of keeping the wafer cassette units 40 clean. Therefore, only the fan output power of the filter unit 80 needs to be increased to make the downflow intensive, and the fan output power of the filter unit 70 may be small. This is because the cleaning section 10 does not need to be cleaner than necessary. Thus, the fan output power of the filter unit 70 may be reduced, and a fan of low output power may be used to reduce the cost thereof, and the operating cost is also lowered.

Please replace the paragraph beginning at page 14, line 23, with the following rewritten paragraph:

As shown in FIGS. 7 through 9, the handling table 50 has a box-shaped frame 51, four support members 52 fixed to a plate 51a on an upper surface of the frame 51 and having inverted conical tapered surfaces 52a for contacting the outer circumferential edge of a semiconductor wafer 6 to support the semiconductor wafer 6, and four positioning members 53 for receiving the semiconductor wafer 6 supported by the support members 52 and rotating the semiconductor wafer 6 in a predetermined angular range. The four positioning members 53 are fixed to a rotatable base 54 which can be rotated by a motor 55. The motor 55 and the rotatable base 54 are supported by a lifting and lowering base 56 which can be lifted and lowered by an air cylinder 57. The reference numeral 60 represents splined shafts.

Please replace the paragraph beginning at page 17, line 24, with the following rewritten paragraph:

After the motor 55 is stopped, the air cylinder 57 is actuated to lower the positioning members 53. The semiconductor wafer 6 is transferred from the positioning members 53 to the support members 52. After the positioning members 52 are lowered, the motor 55 is rotated to return to its home position. When the motor 55 returns to its home position, the home position is detected by the

home-position confirming sensor 67. Then, the SCARA robot 31 receives the semiconductor wafer 6 on the support members 52, and transfers the semiconductor wafer 6 into the wafer cassette 41 in one of the wafer cassette units 40.